

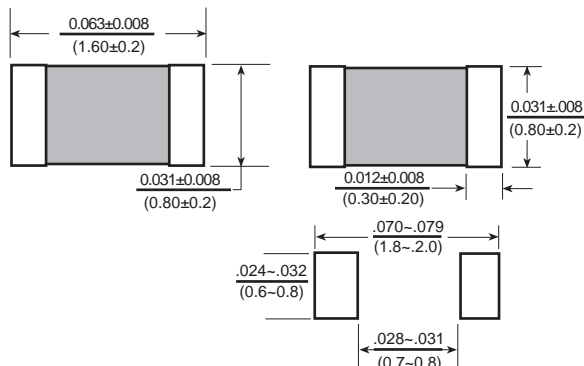


## Multilayer Chip Inductors

## MLC05



Dimensions:  $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Inductance ( $\mu\text{H}$ )	Tolerance (%) *	Q Min.	Test Freq. (MHz)	SRF Min. (MHz)	DCR Max. ( $\Omega$ )	IDC Max. (mA)
MLC05-R033M-RC	.033	M	15	50	270	0.20	50
MLC05-R047M-RC	.047	M	15	50	260	0.30	50
MLC05-R056M-RC	.056	M	15	50	255	0.30	50
MLC05-R068M-RC	.068	M	15	50	250	0.30	50
MLC05-R082M-RC	.082	M	15	50	245	0.30	50
MLC05-R10_-RC	.10	K,M	25	25	240	0.50	50
MLC05-R12_-RC	.12	K,M	25	25	205	0.50	50
MLC05-R15_-RC	.15	K,M	25	25	180	0.60	50
MLC05-R18_-RC	.18	K,M	25	25	165	0.60	50
MLC05-R22_-RC	.22	K,M	25	25	150	0.80	50
MLC05-R27_-RC	.27	K,M	25	25	136	0.80	50
MLC05-R33_-RC	.33	K,M	25	25	125	0.85	35
MLC05-R39_-RC	.39	K,M	25	25	110	1.00	35
MLC05-R47_-RC	.47	K,M	25	25	105	1.35	35
MLC05-R56_-RC	.56	K,M	25	25	95	1.50	35
MLC05-R68_-RC	.68	K,M	25	25	85	1.70	35
MLC05-R82_-RC	.82	K,M	25	25	75	2.10	35
MLC05-1R0_-RC	1.0	K,M	35	10	65	0.60	25
MLC05-1R2_-RC	1.2	K,M	35	10	60	0.80	25
MLC05-1R5_-RC	1.5	K,M	35	10	55	0.80	25
MLC05-1R8_-RC	1.8	K,M	35	10	50	0.95	25
MLC05-2R2_-RC	2.2	K,M	35	10	45	1.10	15
MLC05-2R7_-RC	2.7	K,M	35	10	40	1.30	15
MLC05-3R3_-RC	3.3	K,M	35	10	38	1.50	15
MLC05-3R9_-RC	3.9	K,M	35	10	36	1.70	15
MLC05-4R7_-RC	4.7	K,M	35	10	33	2.10	15
MLC05-5R6_-RC	5.6	K,M	35	4	22	1.50	5
MLC05-6R8_-RC	6.8	K,M	35	4	20	1.70	5
MLC05-8R2_-RC	8.2	K,M	30	4	18	2.10	5
MLC05-100_-RC	10	K,M	30	2	17	2.55	5
MLC05-120_-RC	12	K,M	30	2	15	2.60	3
MLC05-150_-RC	15	K,M	20	1	14	1.50	1
MLC05-220_-RC	22	K,M	20	1	11	1.70	1

\*Please insert the letter for desired tolerance: K=10% M=20%  
All specifications subject to change without notice.

### Features

- 0603 EIA Size
- MultiLayer Ferrite Construction
- Closed Magnetic path for Shielding
- Excellent Solderability Characteristics

### Electrical

**Inductance Range:** .033 $\mu\text{H}$  to 22 $\mu\text{H}$

**Tolerance:** As noted, please indicate letter desired tolerance.

**Test Frequency:** As noted.

**Operating Temp:** -40°C ~ 125°C / -55°C to +125°C pending.

### Resistance to Solder Heat

Pre-Heat: 150°C, 1 minute.

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260°C  $\pm$ 5°C

Immersion time: 10  $\pm$ 1 sec.

No Damage with more than 75% coverage.

Inductance within 30% of initial value. Within 20% over 12 $\mu\text{H}$ .

### Test Equipment

**(L):** HP4291A RF Impedance Analyzer or alternate.

**DCR:** Chen Hwa 502BC or HP4338B or alternate.

**SRF:** HP8753D / Agilent E4991A or alternate.

**IDC:** HP4284A with HP42841A / HP4285A with HP42841A.

### Physical

**Packaging:** 4000 pieces per 7 inch reel.

**Marking:** None